



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	Benfer, David W	Contact Title	Prod Compliance Engineer		
Company Unique ID	TE Connectivity	Response Date	2017-05-11	Contact Email	dave.benfer@te.com				
Contact Phone Number	717-986-3725								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	2041119-1	Amount	1170.7446	Version	-	Identity			
Manufacturer Item Name	mSATA/mini PCI-E 4H Type I G/F	Weight Uom	mg	Mfr Site		Authority			
Date		UOM	Each						
EURoHS-0508	Product(s) meets EU RoHS requirement without any exemptions								
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
EUREACH-0616	REACH Candidate Substances of Very High Concern ARE NOT Contained in the Product Above the Limits per the Definition within REACH								
Complex Article Description	REACH Candidate Substances of Very High Concern according to Once an Article Always an Article are Not Yet Reviewed								
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Material	1	Upper Contact-Au plating				1.0	0.0338	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.3	1.0	1.014E-4	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.0336986	mg	
Material	1	Upper Contact				1.0	171.6	mg	
Substance	2	Zinc	Supplier	7440-66-6	5.0E-4	1.0	8.58E-4	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0081	1.0	0.0138996	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0807	1.0	0.13848	mg	
Substance	2	Copper	Supplier	7440-50-8	94.1562	1.0	161.57204	mg	
Substance	2	Tin	Supplier	7440-31-5	5.6665	1.0	9.72371	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.085	1.0	0.14586	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0030	1.0	0.005148	mg	
Material	1	Lower Contact-Au plating				1.0	0.0208	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.3	1.0	6.24E-5	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.0207376	mg	
Material	1	Solder Pegs				1.0	22.6	mg	
Substance	2	Zinc	Supplier	7440-66-6	35.7546	1.0	8.08054	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0082	1.0	0.0018532	mg	
Substance	2	Copper	Supplier	7440-50-8	64.23	1.0	14.51598	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0015	1.0	3.39E-4	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0057	1.0	0.0012882	mg	
Material	1	Upper Contact-Ni plating				1.0	3.614	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	3.59593	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.4	1.0	0.014456	mg	

Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.003614	mg	
Material	1	Solder Pegs-Ni plating				1.0	0.27	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	2.7E-4	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.4	1.0	0.00108	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	0.26865	mg	
Material	1	Lower Contact-Ni plating				1.0	1.976	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.4	1.0	0.007904	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	1.96612	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.001976	mg	
Material	1	Solder Pegs-Sn plating				1.0	0.53	mg	
Substance	2	Tin	Supplier	7440-31-5	99.9001	1.0	0.52947	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0999	1.0	5.2947E-4	mg	
Material	1	Housing				1.0	884.3	mg	
Substance	2	1,3-Benzenedicarb oxylic acid, polymer with 1,4-benzenedicarb oxylic acid, [1,1-biphenyl]-4,4-diol and 4-hydroxybenzoic acid	Supplier	60088-52-0	100.0	1.0	884.3	mg	
Material	1	Lower Contact				1.0	85.8	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.085	1.0	0.07293	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0807	1.0	0.0692406	mg	
Substance	2	Tin	Supplier	7440-31-5	5.6665	1.0	4.86186	mg	
Substance	2	Zinc	Supplier	7440-66-6	5.0E-4	1.0	4.29E-4	mg	
Substance	2	Copper	Supplier	7440-50-8	94.1562	1.0	80.78602	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0081	1.0	0.0069498	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0030	1.0	0.002574	mg	